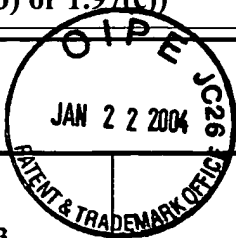


**TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT**  
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.  
AM-5209-D2

In Re Application: Ling CHEN et al.



Serial No.  
10/693,775

Filing Date  
October 24, 2003

Examiner  
unknown

Group Art Unit  
unknown

Tantalum Barrier Layer for Copper Metallization

**Payment of Fee**

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- ☐ A check in the amount of \_\_\_\_\_ is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. 50-0636 as described below. A duplicate copy of this sheet is enclosed.
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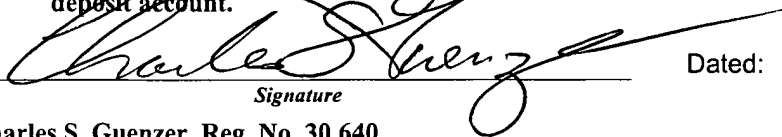
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Dated: January 13, 2004

Charles S. Guenzer, Reg. No. 30,640  
(650) 566-8040

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Applied Materials, Inc.

Patent/Legal Department

P.O. Box 450A

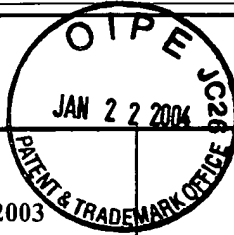
Santa Clara, CA 95052

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**TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT**  
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Examiner  
unknown

Group Art Unit  
unknown

Title: **Tantalum Barrier Layer for Copper Metallization**

Address to:  
Assistant Commissioner for Patents  
Washington, D.C. 20231

**37 CFR 1.97(b)**

1. ☒ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

**37 CFR 1.97(c)**

2. ☐ The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:
- ☐ the statement specified in 37 CFR 1.97(e);
- OR**
- ☐ the fee set forth in 37 CFR 1.17(p).

U.S. Department of Commerce, Patent and Trademark Office					Docket No.: <b>AM-5209.D2</b>		
					Serial No.: 10/693,775		
LIST OF RELEVANT ART CITED BY APPLICANT					Applicant: Ling Chen et al.		
(Use several sheets if necessary)					Filing Date: October 24, 2003		
					Group: Unknown		

U.S. PATENT DOCUMENTS							
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA	5,770,519	Klein et al.	438	639		
	AB	5,846,332	Zhao et al.	118	728		
	AC	5,933,753	Simon et al.	438	629		
	AD	5,985,762	Geffken et al.	438	687		
	AE	6,106,625	Koai et al.	118	715		
	AF	6,265,313	Huang et al.	438	687		
	AG	6,277,249	Gopalraja et al.	204	192.12		
	AH	6,284,657	Chooi et al.	438	687		
	AI	6,287,977	Hashim et al.	438	722		
	AJ	6,294,458	Zhang et al.	438	627		
	AK	6,306,732	Brown	438	468		
FOREIGN PATENT DOCUMENTS (Translation)							
	Document Number	Date	Country	Class	Subclass	Yes	No
	AL	XP-002223600	Japan			Abstract	
	AM	2000-323571	Japan			Abstract	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
	AR	Yamagihshi et al., "TEM/SEM Investigation and Electrical Evaluation of a Bottomless 1-PVS Ta(N) Barrier in a Dual Mask", <i>Advanced Metallization Conference 2000, Proceedings of the Conference 2000, Advanced Metallization Conference 2000, Proceedings of the Conference, San Diego, CA, USA, October 2-5, 2000, 279-285 pp.</i>					
	AS						
	AT						
Examiner			Date Considered				

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.